Alan Mantooth – University of Arkansas

POETS

AN NSF SPONSORED CENTER

- Electronic design automation tools
- 3D Packaging
- Analog IC Design
- Semiconductor Device Modeling

http://eleg.uark.edu/

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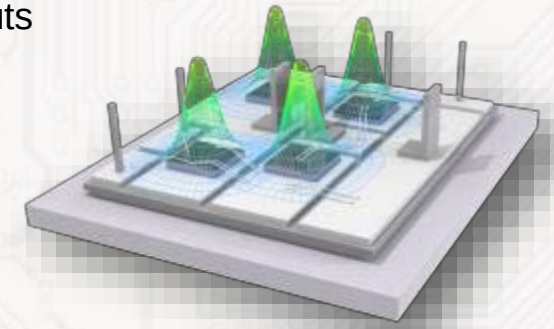
Design Automation Tools

PowerSynth

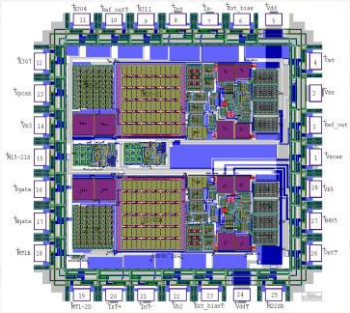
- Electrical and Thermal Modeling
- Fast Multi-objective Optimization of Multi-Chip Power Module Layouts
- Software Design
- Import and Export
- Physical Validation



Analog IC Design

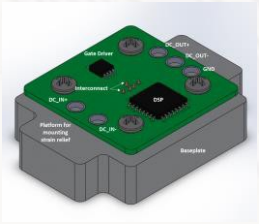
High temperature and high efficiency integrated circuits

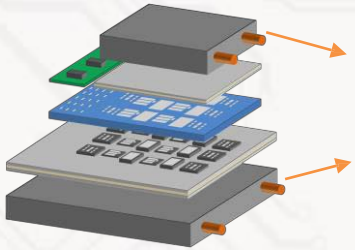
- Semiconductor modeling
- Model-based design approach
- Design and verification
- Physical design – layout
- Post-layout analysis
- Test over extreme temps



3D Packaging

Wire bondless Integrated Power Modules





Double sided cooling capability to facilitate heat removal

High density electronic modules, with low parasitics and ultrafast switching capability suitable for wide bandgap semiconductors